



FEATURES

- ✧ 400 watts peak pulse power per line ($t_P=8/20\mu s$)
- ✧ Protects one bi-directional I/O line
- ✧ Low clamping voltage
- ✧ Working voltage: 5V
- ✧ Low leakage current
- ✧ RoHS compliant
- ✧ Meets MSL level 3

MAIN APPLICATIONS

- ✧ Cell phone handsets and accessories
- ✧ Microprocessor based equipment
- ✧ Personal digital assistants (PDA's)
- ✧ Notebooks, desktops, and servers
- ✧ Portable instrumentation
- ✧ Peripherals
- ✧ USB interface

PROTECTION SOLUTION TO MEET

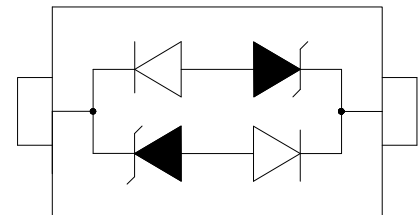
- ✧ IEC61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ IEC61000-4-5 (lightning) 17A (8/20 μs)

MECHANICAL CHARACTERISTICS

- ✧ SOD-323 package
- ✧ Molding compound flammability rating: UL 94V-0
- ✧ Weight 5 milligrams (approximate)
- ✧ Quantity per reel: 3,000pcs
- ✧ Lead finish: lead free
- ✧ Marking code:5B



SOD-323



Pin Configuration

ABSOLUTE MAXIMUM RATINGS ($T_A=25^{\circ}\text{C}$, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20 μs waveform	P_{PP}	400	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	+/- 30 +/- 30	kV
Lead soldering temperature	T_L	260 (10 sec.)	$^{\circ}\text{C}$
Operating junction temperature range	T_J	-55 to +125	$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS ($T_A=25^{\circ}\text{C}$)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V_{RWM}				5.0	V
Reverse breakdown voltage	V_{BR}	$I_T=1\text{mA}$	6.0			V
Reverse leakage current	I_R	$V_{RWM}=5\text{V}$			1	μA
Clamping voltage	V_C	$I_{PP}=1\text{A}$, $t_P=8/20\mu\text{s}$			9.8	V
		$I_{PP}=17\text{A}$, $t_P=8/20\mu\text{s}$			25	V
Junction capacitance	C_J	$V_{RWM}=0\text{V}$, $f=1\text{MHz}$		1.0	1.5	pF

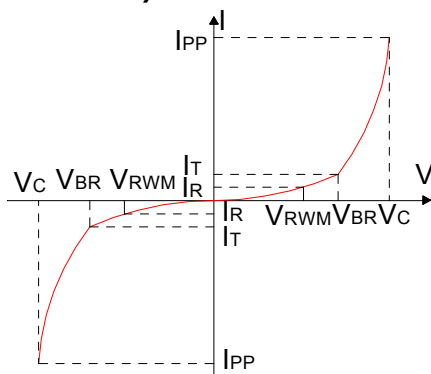
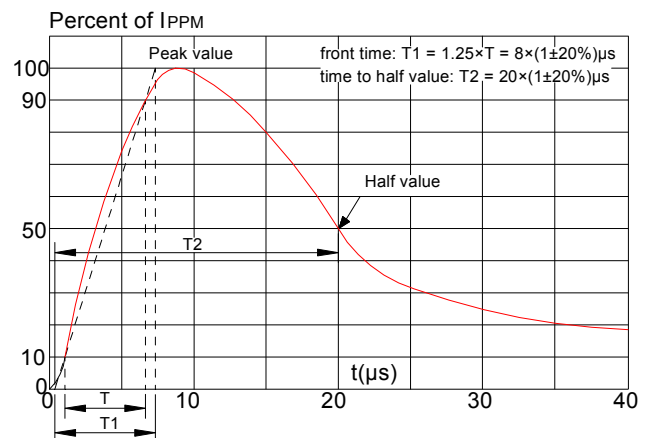
RATINGS AND V-I CHARACTERISTICS CURVES ($T_A=25^{\circ}\text{C}$, unless otherwise noted)**FIG.1:V- I curve characteristics (Bi-directional)****FIG.2: Pulse waveform (8/20 μs)**

FIG.3: Pulse derating curve

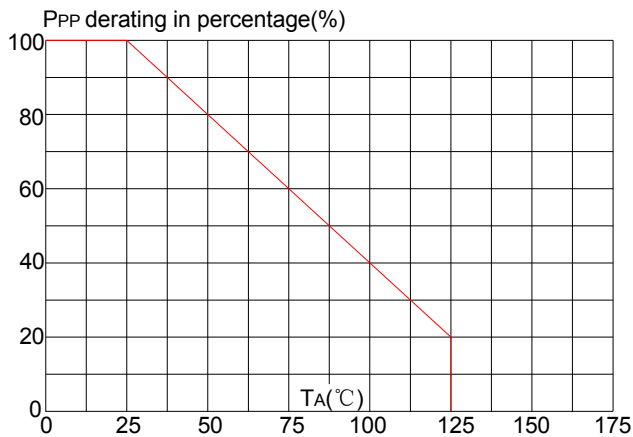
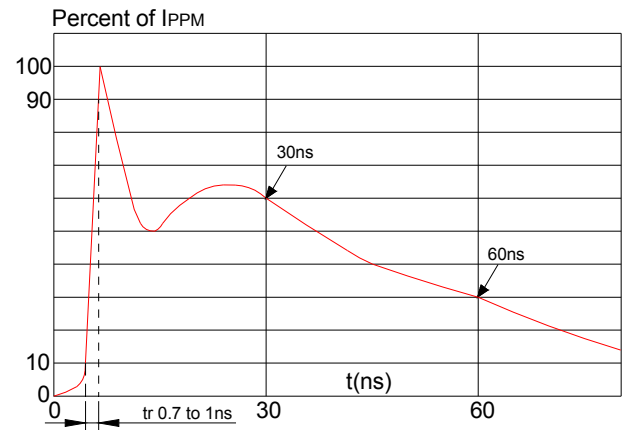
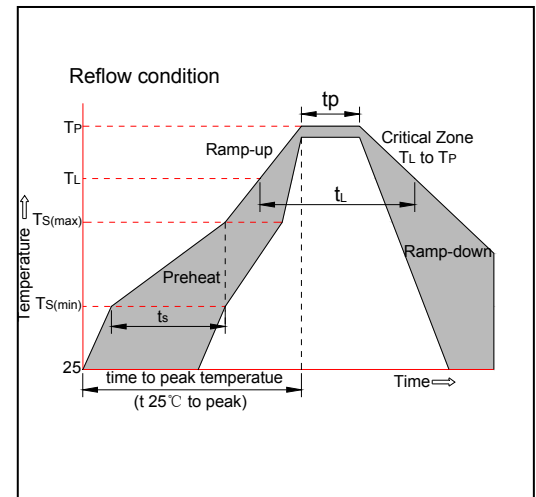


FIG.4: ESD clamping (30kV contact)

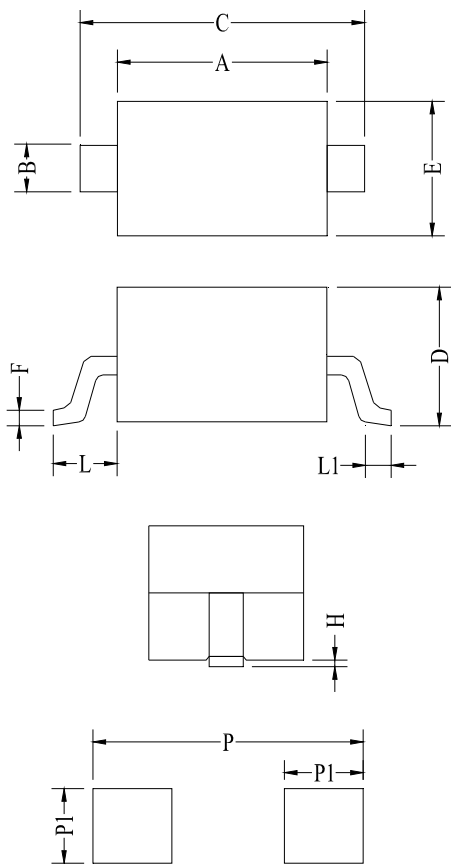


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max ($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature (T_L) (Liquidus)	+217°C
	-Temperature (t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_P)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



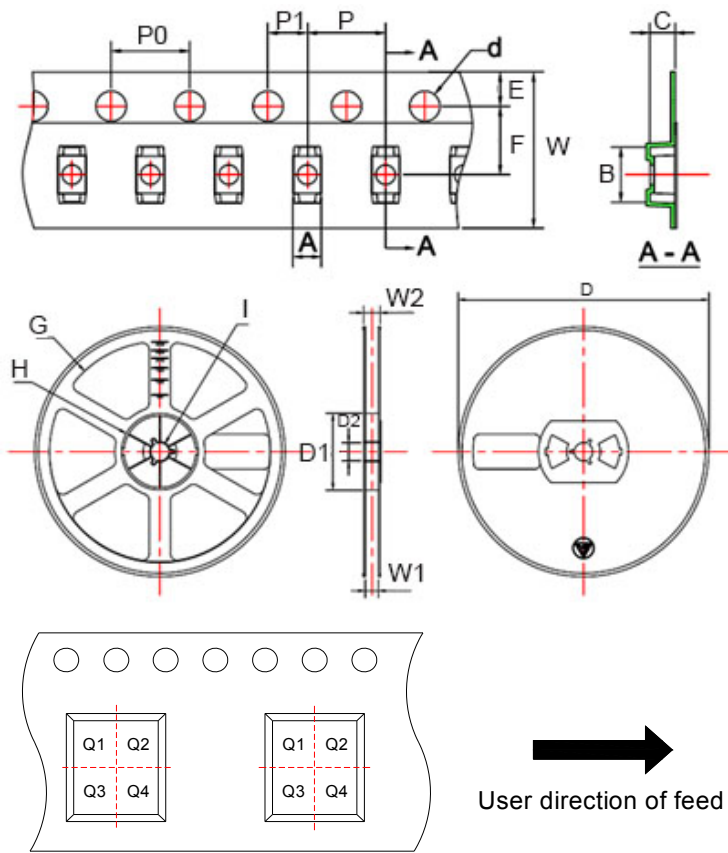
PACKAGE MECHANICAL DATA



Land Pattern

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	1.60	1.70	1.80	0.063	0.067	0.071
B	0.25	0.32	0.40	0.010	0.013	0.016
C	2.30	2.60	2.80	0.091	0.102	0.110
D	0.80	0.95	1.10	0.031	0.037	0.043
E	1.20	1.30	1.40	0.047	0.051	0.055
F	0.08	0.13	0.18	0.003	0.005	0.007
L	0.475REF			0.019REF		
L1	0.25	0.33	0.40	0.010	0.013	0.016
H	0.00	0.06	0.14	0.000	0.002	0.006
P	3.00			0.118		
P1	0.80			0.031		

TAPE AND REEL INFORMATION-SOD-323



Pin 1 quadrant:Q1&Q2

Packaging description:

SOD-323 parts are shipped in tape. The carrier tape is made from a dissipative(carbon filled) polycarbonate resin. The cover tape is a multilayer film(heat activated adhesive in nature)primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. The reels are blue in color and made of recyclable plastic.

Symbol	Millimeters	Inches
	Typ	Typ
A	1.46	0.057
B	2.90	0.114
C	1.25	0.049
d	ø1.50	ø0.059
E	1.75	0.069
F	3.50	0.138
P0	4.00	0.157
P	4.00	0.157
P1	2.00	0.079
W	8.00	0.315
D	ø178.0	ø7.008
D1	54.40	2.142
D2	13.00	0.512
G	R78.0	R3.071
H	R25.60	R1.008
I	R6.50	R0.256
W1	9.50	0.374
W2	12.30	0.484

ORDERING INFORMATION

PART No.	PACKAGE TYPE	QUANTITY(PCS) REEL	DESCRIPTION
JEB05C	SOD-323	3,000	7 inch reel pack

MARKING CODE

Part Number	Marking Code
JEB05C	

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